



CG8179AA Status: **In Production**

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CG8179AA	
Automotive Qualified	N
Slider Segments	N/A
Min. Operating Voltage (V)	1.71
Max. Operating Voltage (V)	5.50
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	85
No. of GPIOs	10
No. of CapSense IO	10
Proximity Sensing	Y
SmartSense Enabled	Y
No. of GPOs	5
Comm. Interface	I2C,GPO
PWMs	N
CapSense	Y

Pricing & Inventory Availability					
1-9 unit Price*	10-24 unit Price*	25-99 unit Price*	100-249 unit Price*	250-999 unit Price*	1000 + unit Price*
..					
Availability	Quantity	Ships In	Order Now		

* Prices are shown in United States dollars and are for budgetary use only for volume of 1ku

Packaging/Ordering	
Package	SOIC
No. of Pins	16
Package Dimensions	390 L X 1.47 H X 150 W (Mils)
Package Weight	157.31 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TUBE
Package Carrier Drawing / Orientation	Drawing, Package Orientation
Standard Pack Quantity	720
Minimum Order Quantity (MOQ)	720
Order Increment	720

Estimated Lead Time (days)	28
HTS Code	8542.31.0000
ECCN	EAR99

Quality and RoHS	
Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format
Package Material Declaration	
16L - SOIC 150 MILS PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET <i>Last Update: 08/08/2014</i>	
IPC 1752 Material Declaration	
IPC-1752-2_V1.1_SOIC16_AMKOR_150MILS <i>Last Update: 06/19/2014</i>	
IPC-1752-2_V1.1_SOIC16_CML_150MILS <i>Last Update: 06/19/2014</i>	
IPC-1752-2_V1.1_SOIC16_OSE_150MILS <i>Last Update: 06/19/2014</i>	
RoHS Analysis Certificates (CoA)	
PACKAGE ROHS ANALYSIS REPORT - SOIC (SZ08,16,18,20,24) USING MOLD COMPOUND MP8500, ADHESIVE QMI509, NIPDAU - CML ASSEMBLY <i>Last Update: 07/03/2012</i>	
PACKAGE ROHS ANALYSIS REPORT - SSOP (SP 20,28,48,56) SOIC (SZ08,14,16) USING MOLD COMPOUND CEL9220HF, ADHESIVE 4900G, NIPDAU - OSE TAIWAN ASSEMBLY <i>Last Update: 07/04/2012</i>	
Device Qualification Reports	
 FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. 001-91143_0A_V.pdf <i>Last Update: 03/20/2014</i>	

Technical Documents
Application Notes (0)
Product Information Notice (PIN) (1) PIN145347 <i>Last Update: 17/12/2014</i>

Support and Community
Cypress Developer Community ™
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Blogs
Support
Knowledge Base
Product Training